

STB75NF75L

N-channel 75V - 0.009Ω - 75A - D²PAK STripFET™ II Power MOSFET

Features

Туре	V _{DSS}	R _{DS(on)}	I _D
STB75NF75L	75V	<0.011Ω	75A

- Exceptional dv/dt capability
- 100% avalanche tested
- Low threshold drive

Description

This MOSFET series realized with STMicroelectronics unique STripFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced highefficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any applications with low gate drive requirements.

Applications

Switching applications

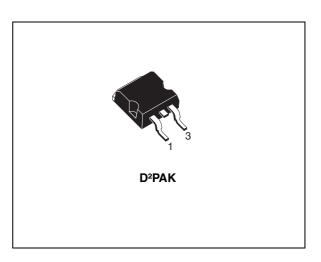
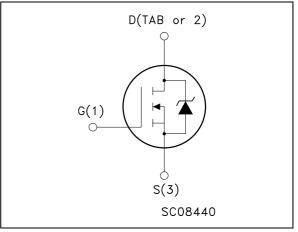


Figure 1. Internal schematic diagram



Order code	Marking	Package	Packaging
STB75NF75LT4	B75NF75L	D ² PAK	Tape & reel

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Electrical ratings

Table 2. Absolute maximum ratings	Table 2.	Absolute	maximum	ratings
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Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage ($V_{GS} = 0$)	75	V
V _{GS}	Gate-source voltage	± 15	V
I _D ⁽¹⁾	Drain current (continuous) at $T_C = 25^{\circ}C$	75	А
I _D	Drain current (continuous) at $T_C = 100^{\circ}C$	70	А
I _{DM} ⁽²⁾	Drain current (pulsed)	300	А
P _{TOT}	Total dissipation at $T_C = 25^{\circ}C$	300	W
	Derating factor	2	W/°C
dv/dt ⁽³⁾	Peak diode recovery voltage slope	10	V/ns
E _{AS} ⁽⁴⁾	Single pulse avalanche energy	680	mJ
T _J T _{stg}	Operating junction temperature Storage temperature	-55 to 175	°C

1. Current limited by package

2. Pulse width limited by safe operating area

3. $I_{SD} \leq 75A$, di/dt $\leq 500A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$, $T_j \leq T_{JMAX}$

4. Starting $T_J = 25$ °C, $I_D = 37.5A$, $V_{DD} = 30V$

Table 5. Thermal uata	Table	3.	Thermal	data
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Symbol	Parameter	Value	Unit
R _{thJC}	Thermal resistance junction-case Max	0.5	°C/W
R _{thJA}	Thermal resistance junction-ambient Max	62.5	°C/W
Τ _Ι	Maximum lead temperature for soldering purpose	300	°C

2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_{D} = 250 \mu A, V_{GS} = 0$	75			V
I _{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	V _{DS} = Max rating, V _{DS} = Max rating @125°C			1 10	μΑ μΑ
I _{GSS}	Gate body leakage current (V _{DS} = 0)	$V_{GS} = \pm 15V$			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1		2.5	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10V, I _D = 37.5A V _{GS} = 5V, I _D = 37.5A		0.009 0.010	0.011 0.013	Ω Ω

Table 4. On/off states

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 _{fs} ⁽¹⁾	Forward transconductance	V _{DS} = 15V, I _D = 37.5A		120		S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} =25V, f = 1 MHz, V _{GS} = 0		4300 660 205		pF pF pF
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 60V, I_D = 75A$ $V_{GS} = 5V$ see <i>Figure 15</i>		75 18 31	90	nC nC nC

1. Pulsed: pulse duration=300µs, duty cycle 1.5%

Table 0.	Switching times					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r t _{d(off)} t _f	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD} = 40V, I_D = 37.5A,$ $R_G = 4.7\Omega, V_{GS} = 4.5V$ see <i>Figure 14</i>		35 155 110 60		ns ns ns ns

Table 6. Switching times



Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
I _{SD}	Source-drain current				75	А
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)				300	А
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 75A, V_{GS} = 0$			1.3	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I _{SD} = 75A, di/dt = 100A/μs, V _{DD} = 24V, T _J = 150°C see <i>Figure 16</i>		120 500 9		ns nC A

Table 7.Source drain diode

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration=300µs, duty cycle 1.5%

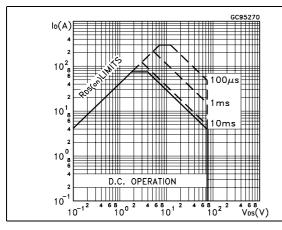


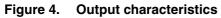
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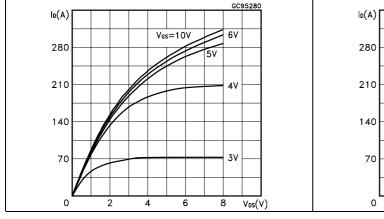
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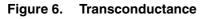
Electrical characteristics (curves) 2.1

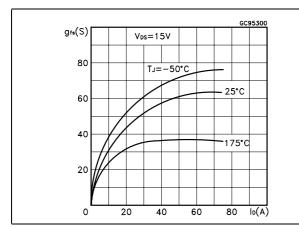
Figure 2. Safe operating area



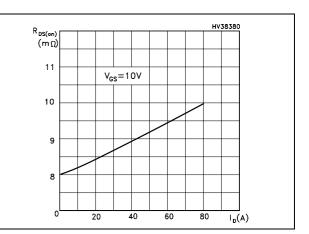




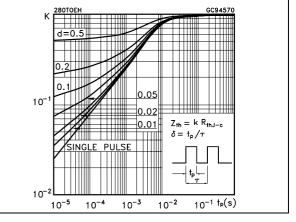








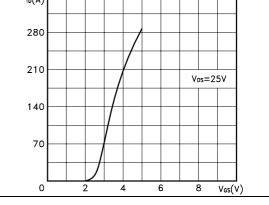
Transfer characteristics



Thermal impedance

Figure 5.

Figure 3.



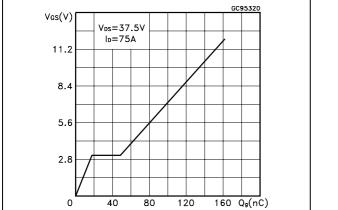
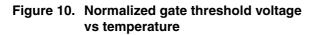


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations



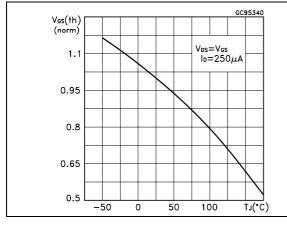


Figure 12. Source-drain diode forward characteristics

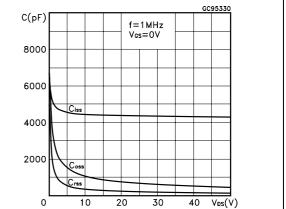


Figure 11. Normalized on resistance vs temperature

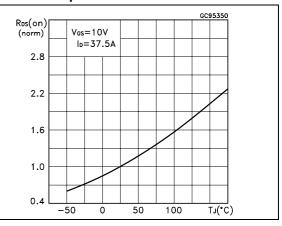
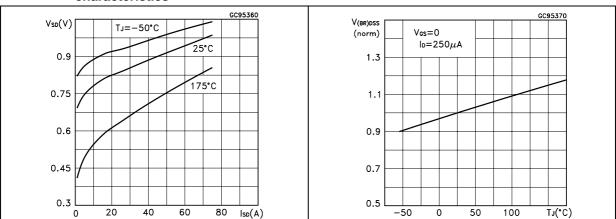
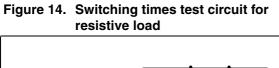


Figure 13. Normalized B_{VDSS} vs temperature



3 Test circuit



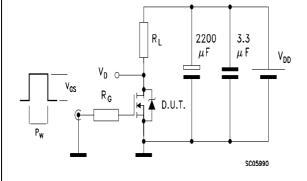
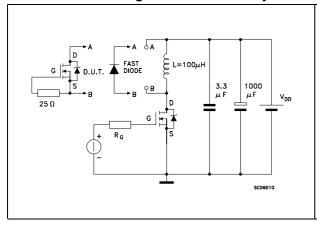
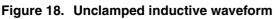
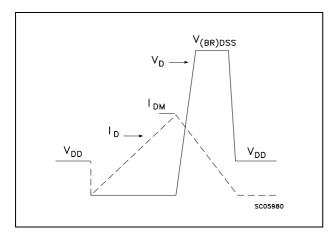


Figure 16. Test circuit for inductive load switching and diode recovery times







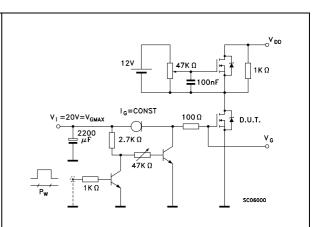
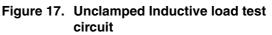
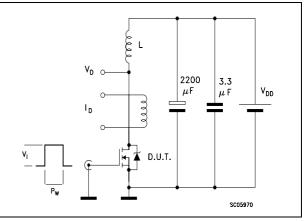


Figure 15. Gate charge test circuit





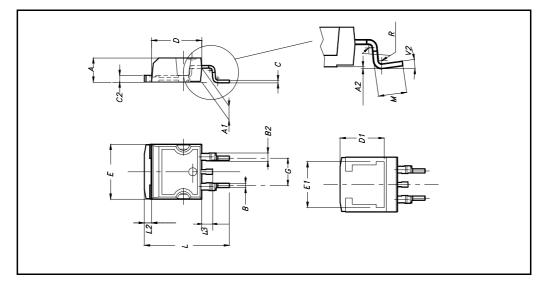
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

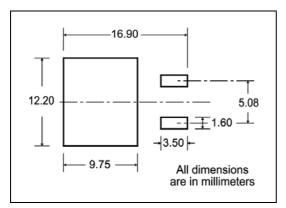


DIM.	mm.			inch		
	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
В	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
С	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
М	2.4		3.2	0.094		0.126
R		0.4			0.015	

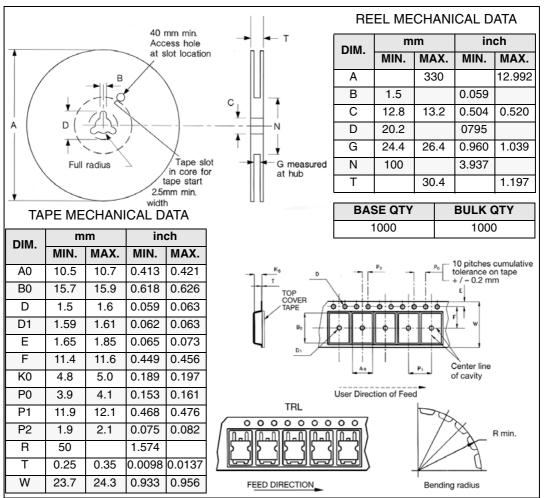
D²PAK MECHANICAL DATA



Packaging mechanical data D²PAK FOOTPRINT



TAPE AND REEL SHIPMENT



* on sales type

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6 Revision history

Date	Revision	Changes
21-Jun-2004	1	First release
02-Oct-2006	2	New template, no content change
13-Jul-2007	3	New updates on Table 7

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